

## General Description

Din-Tek Field Stop Trench IGBTs offer low switching losses, high energy efficiency and short circuit ruggedness.

It is designed for applications such as motor control, uninterrupted power supplies(UPS), general inverters.

## FEATURES

- High speed switching
- High ruggedness, temperature stable behavior
- Short Circuit Withstand Times 10us
- Extremely enhanced avalanche capability

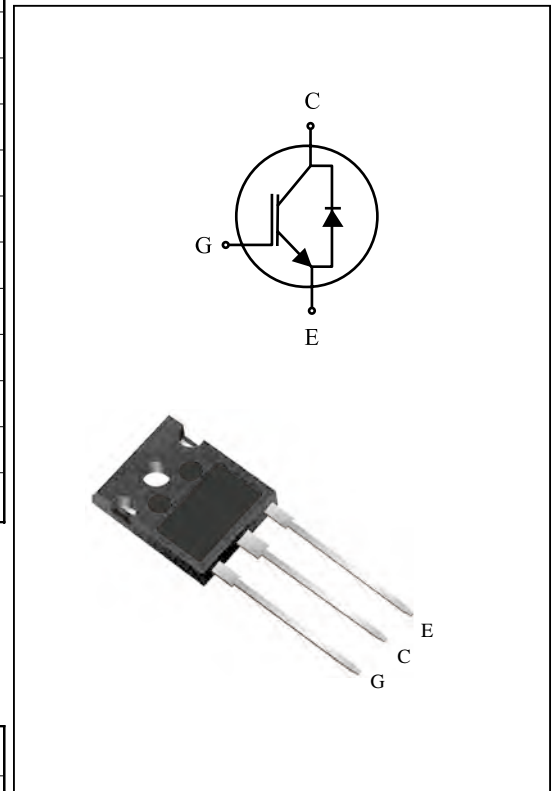
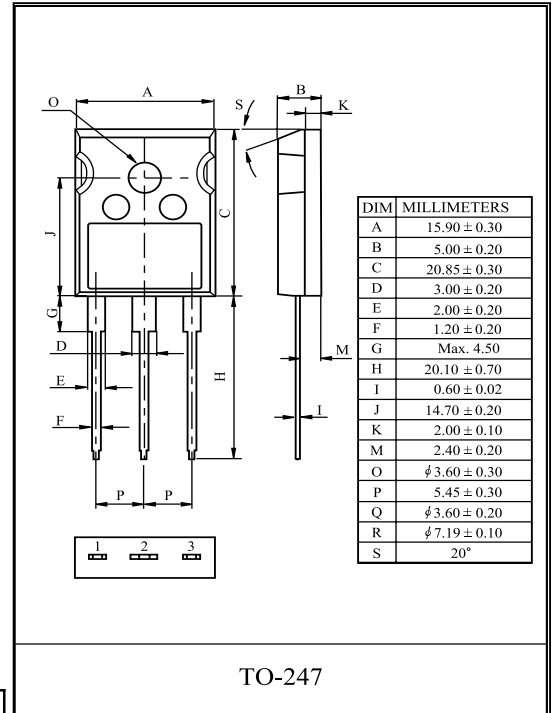
## MAXIMUM RATING (Ta=25 °C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Collector-Emitter Voltage		$V_{CES}$	600	V
Gate-Emitter Voltage		$V_{GES}$	$\pm 20$	V
Collector Current	@Tc=25	$I_C$	100	A
	@Tc=100		50	A
Pulsed Collector Current		$I_{CM}^*$	150	A
Diode Continuous Forward Current	@Tc=100	$I_F$	50	A
Diode Maximum Forward Current		$I_{FM}$	100	A
Maximum Power Dissipation	@Tc=25	$P_D$	277	W
	@Tc=100		111	W
Maximum Junction Temperature		$T_j$	150	
Storage Temperature Range		$T_{stg}$	-55 to + 150	

\*Repetitive rating : Pulse width limited by max. junction temperature

## THERMAL CHARACTERISTIC

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Junction to Case (IGBT)	$R_{thJC}$	0.45	/W
Thermal Resistance, Junction to Case (DIODE)	$R_{thJC}$	1.0	/W
Thermal Resistance, Junction to Ambient	$R_{thJA}$	40	/W



**ELECTRICAL CHARACTERISTICS (Ta=25 °C)**

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Static							
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	V <sub>GE</sub> =0V , I <sub>C</sub> =250 μA	600	-	-	V	
Collector Cut-off Current	I <sub>CES</sub>	V <sub>GE</sub> =0V, V <sub>CE</sub> =600V	-	-	250	μA	
Gate Leakage Current	I <sub>GES</sub>	V <sub>CE</sub> =0V, V <sub>GE</sub> = ± 20V	-	-	± 100	nA	
Gate Threshold Voltage	V <sub>GE(th)</sub>	V <sub>GE</sub> =V <sub>CE</sub> , I <sub>C</sub> =5mA	4.5	5.5	7	V	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	V <sub>GE</sub> =15V, I <sub>C</sub> =50A	-	1.65	2.1	V	
		V <sub>GE</sub> =15V, I <sub>C</sub> =100A	-	2.25	-	V	
		V <sub>GE</sub> =15V, I <sub>C</sub> =50A, T <sub>C</sub> = 125	-	1.9	-	V	
Dynamic							
Total Gate Charge	Q <sub>g</sub>	V <sub>CC</sub> =300V, V <sub>GE</sub> =15V, I <sub>C</sub> = 50A	-	200	-	nC	
Gate-Emitter Charge	Q <sub>ge</sub>		-	30	-	nC	
Gate-Collector Charge	Q <sub>gc</sub>		-	100	-	nC	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>CC</sub> =300V, I <sub>C</sub> =50A, V <sub>GE</sub> =15V,R <sub>G</sub> =10 Inductive Load, T <sub>C</sub> = 25 (Note 1)	-	60	-	ns	
Rise Time	t <sub>r</sub>		-	45	-	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	250	-	ns	
Fall Time	t <sub>f</sub>		-	40	-	ns	
Turn-On Switching Loss	E <sub>on</sub>		-	1.25	1.65	mJ	
Turn-Off Switching Loss	E <sub>off</sub>		-	0.95	1.25	mJ	
Total Switching Loss	E <sub>ts</sub>		-	2.2	2.9	mJ	
Turn-On Delay Time	t <sub>d(on)</sub>		V <sub>CC</sub> =300V, I <sub>C</sub> =50A, V <sub>GE</sub> =15V, R <sub>G</sub> =10 Inductive Load, T <sub>C</sub> = 125 (Note 1)	-	60	-	ns
Rise Time	t <sub>r</sub>			-	50	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	-		260	-	ns	
Fall Time	t <sub>f</sub>	-		50	-	ns	
Turn-On Switching Loss	E <sub>on</sub>	-		1.25	-	mJ	
Turn-Off Switching Loss	E <sub>off</sub>	-		1.15	-	mJ	
Total Switching Loss	E <sub>ts</sub>	-		2.4	-	mJ	
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> =30V, V <sub>GE</sub> =0V, f=1MHz	-	4000	5200	pF	
Ouput Capacitance	C <sub>oes</sub>		-	250	-	pF	
Reverse Transfer Capacitance	C <sub>res</sub>		-	150	-	pF	
Short Circuit Withstand Time	t <sub>sc</sub>	V <sub>CC</sub> =300V, V <sub>GE</sub> =15V, T <sub>C</sub> =100	10	-	-	μs	

Note 1 : Energy loss include tail current and diode reverse recovery.

**ELECTRICAL CHARACTERISTIC OF DIODE**

CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Diode Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 50A	T <sub>C</sub> =25	-	1.8	2.5	V
			T <sub>C</sub> =125	-	1.9	-	
Diode Reverse Recovery Time	t <sub>rr</sub>	V <sub>CC</sub> =300V, I <sub>F</sub> = 50A di/dt = 600A/ μs	T <sub>C</sub> =25	-	100	-	ns
			T <sub>C</sub> =125	-	175	-	
Diode Peak Reverse Recovery Current	I <sub>rr</sub>		T <sub>C</sub> =25	-	19	-	A
			T <sub>C</sub> =125	-	22	-	
Diode Reverse Recovery Charge	Q <sub>rr</sub>		T <sub>C</sub> =25	-	1.1	-	μC
			T <sub>C</sub> =125	-	2.3	-	

Fig 1. Saturation Voltage Characteristics

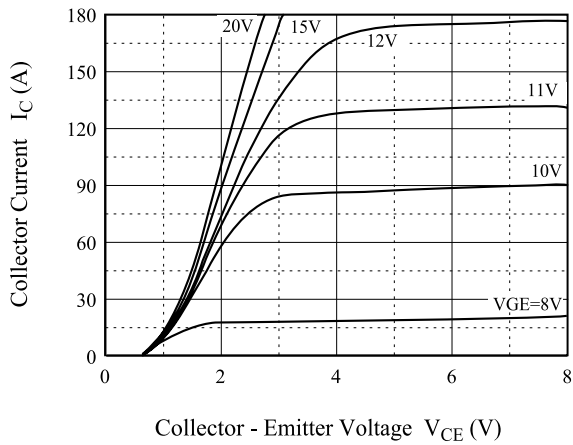


Fig 2. Saturation Voltage Characteristics

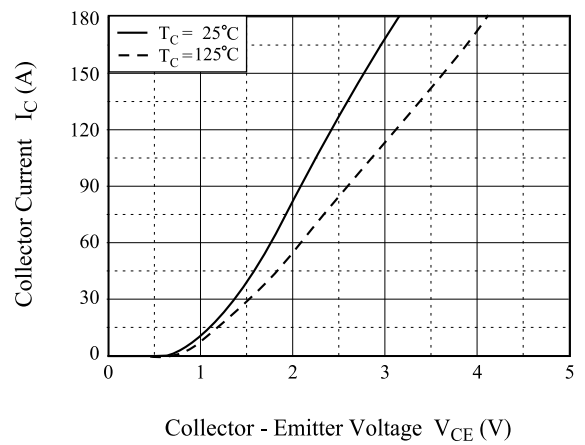


Fig 3. Saturation Voltage vs. Case Temperature

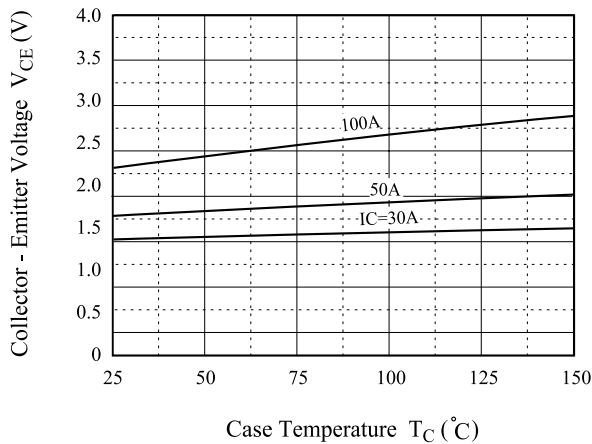


Fig 4. Saturation Voltage vs.  $V_{GE}$

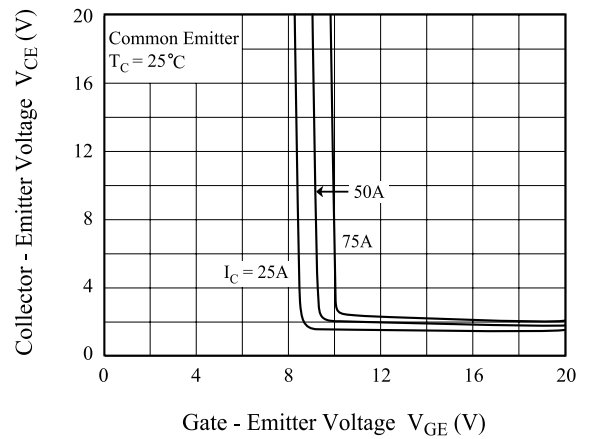


Fig 5. Saturation Voltage vs.  $V_{GE}$

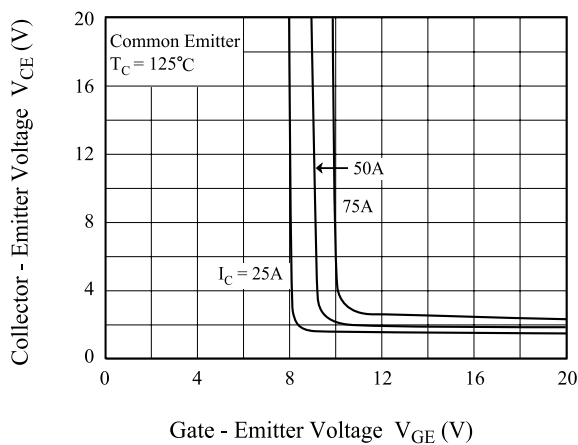


Fig 6. Capacitance Characteristics

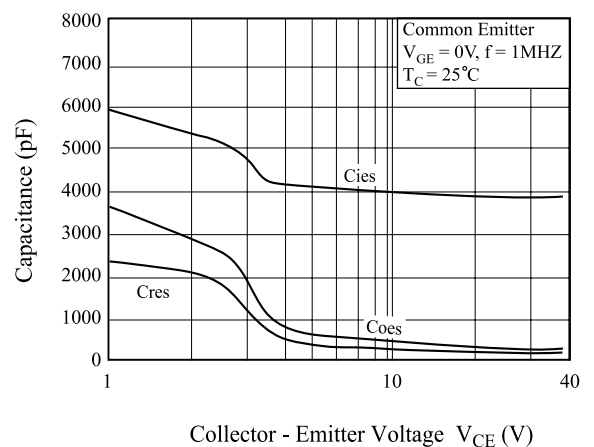


Fig 7. Turn-On Characteristics vs. Gate Resistance

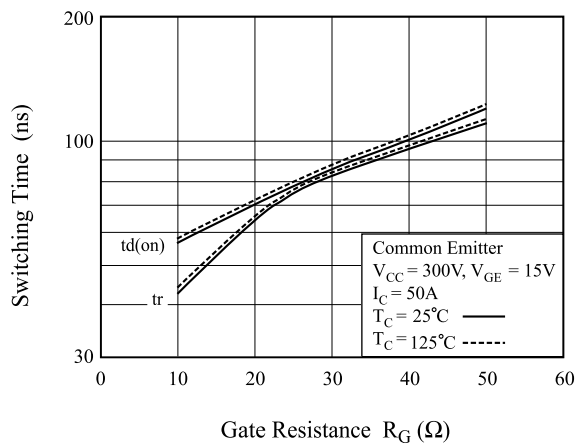


Fig 8. Turn-Off Characteristics vs. Gate Resistance

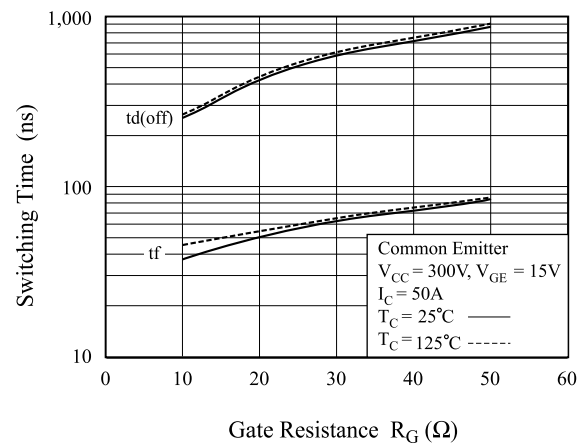


Fig 9. Switching Loss vs. Gate Resistance

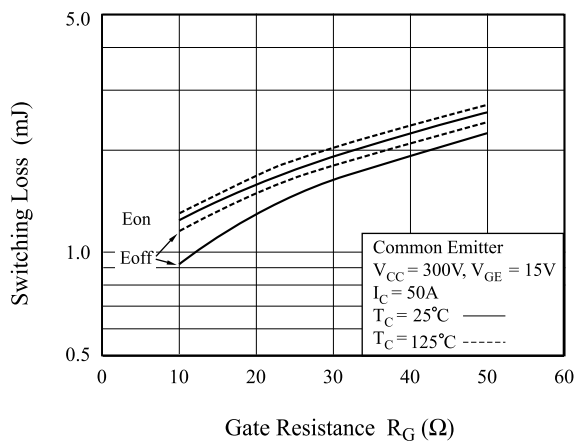


Fig 10. Turn-On Characteristics vs. Collector Current

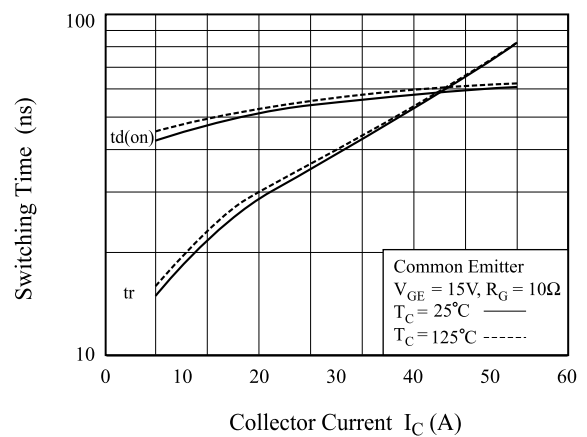


Fig 11. Turn-Off Characteristics vs. Collector Current

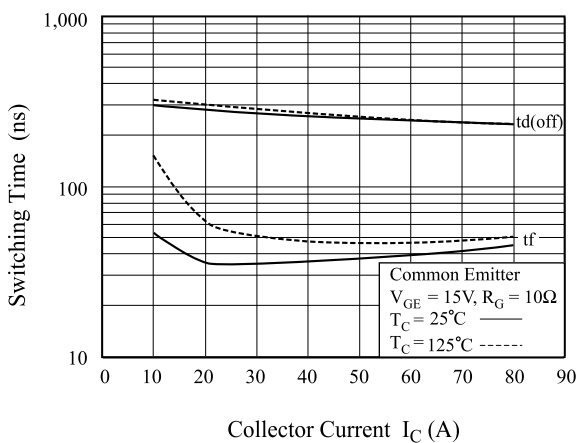


Fig 12. Switching Loss vs. Collector Current

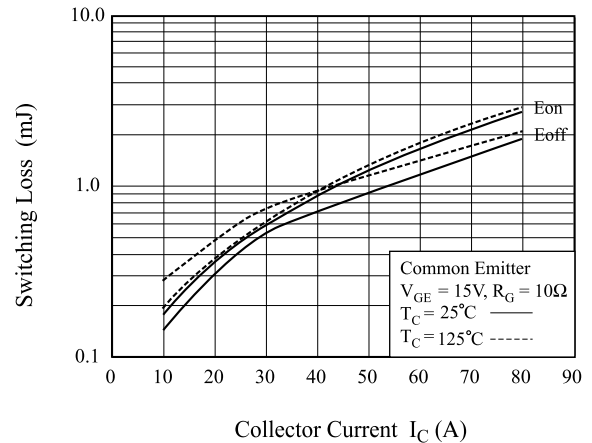


Fig 13. Gate Charge Characteristics

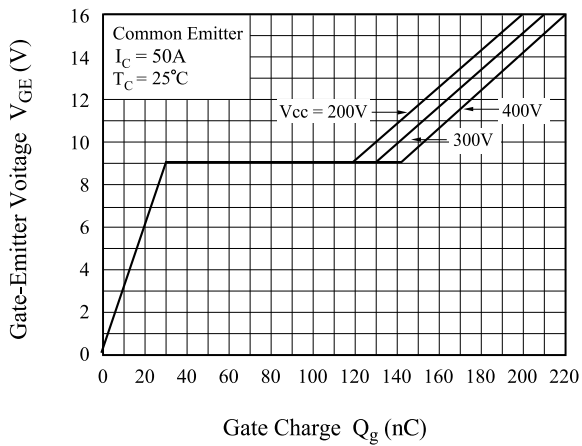


Fig 14. SOA Characteristics

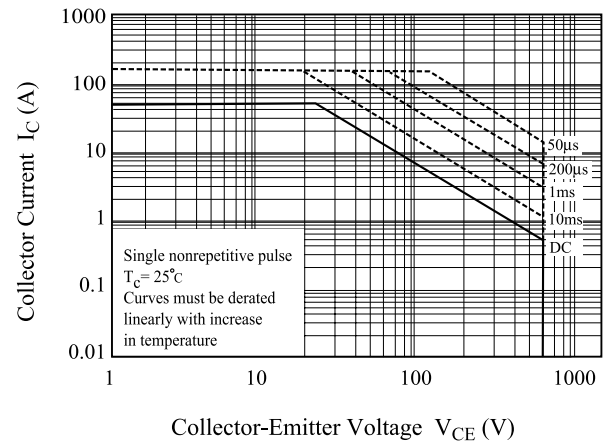


Fig 15. Turn-Off SOA

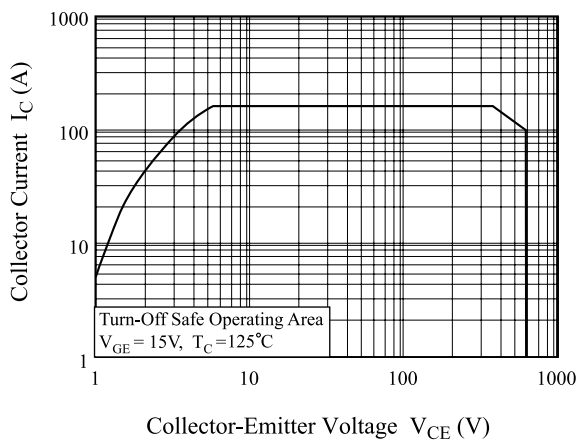


Fig 16. Transient Thermal Impedance of IGBT

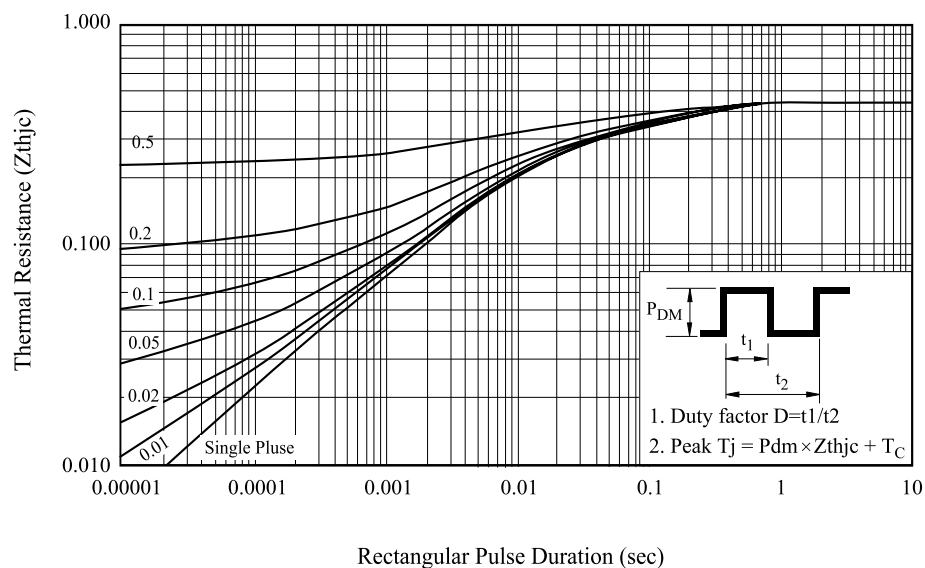


Fig 18. Forward Characteristics

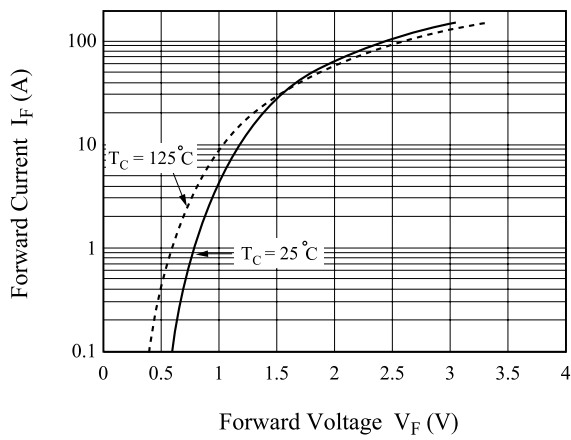


Fig 19. Reverse Recovery Current

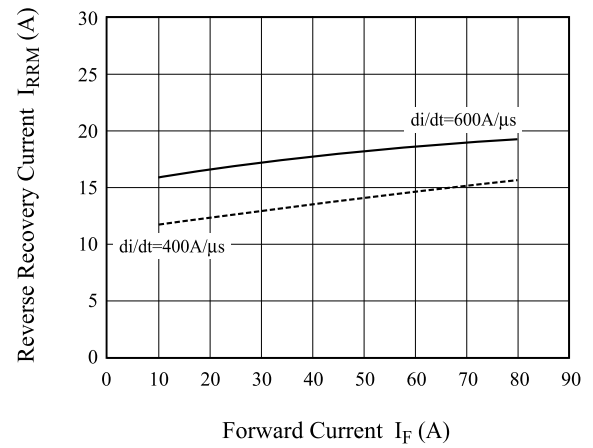


Fig 20. Reverse Recovery Time

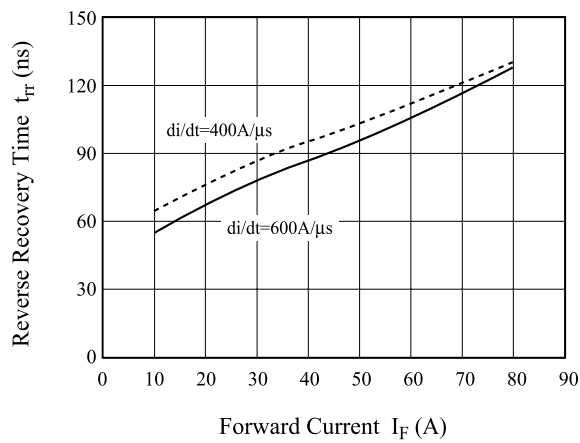


Fig 21. Switching Test Circuit

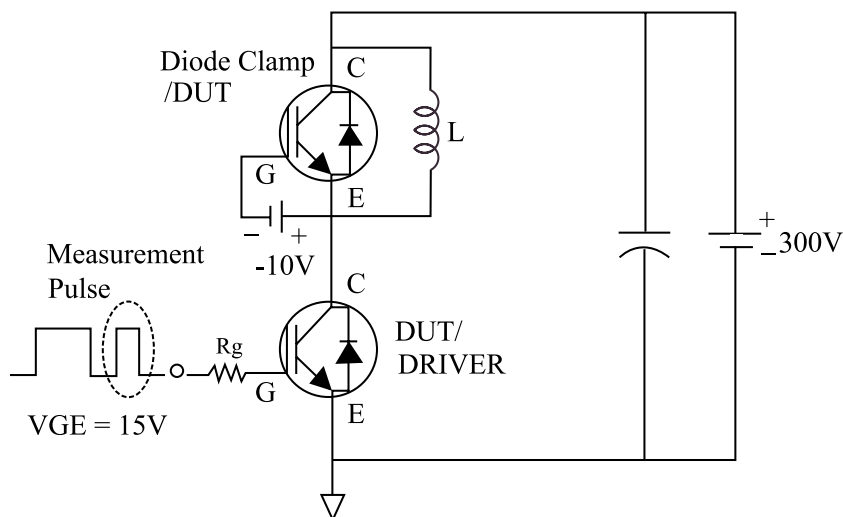


Fig 22. Definition Switching Time & Loss

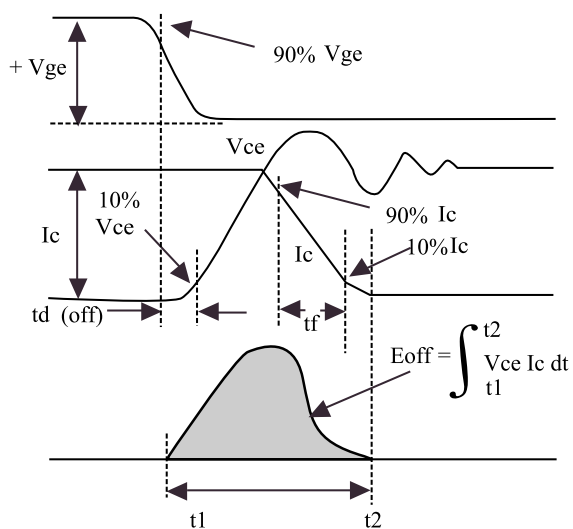
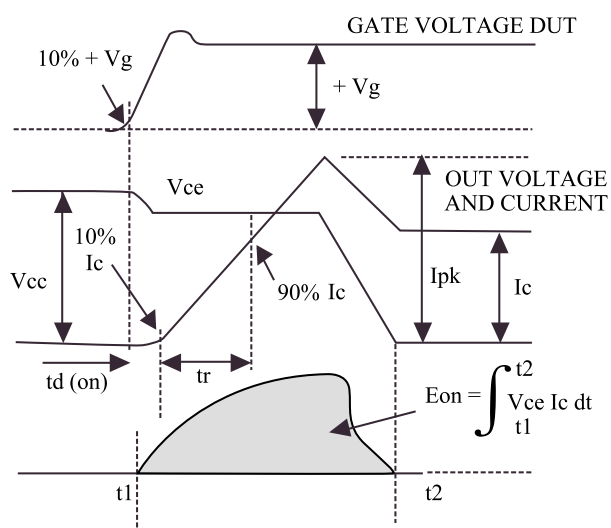
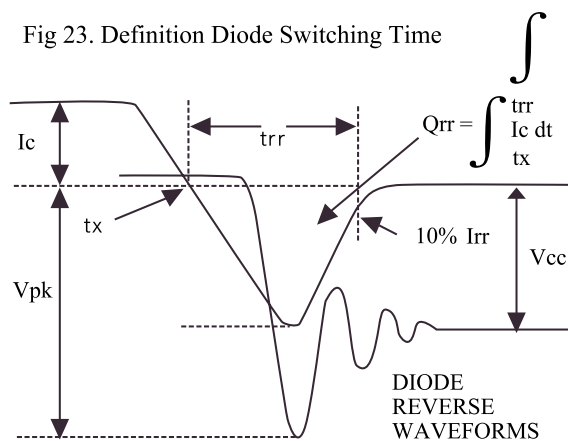


Fig 23. Definition Diode Switching Time





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